

Silicon Carbide (SiC) **Schottky Diode** - EliteSiC, 40 A, 650 V, D1, TO-247-2L

FFSH4065A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

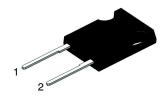
- Max Junction Temperature 175°C
- Avalanche Rated 182 mJ

- No Reverse Recovery/No Forward Recovery
 This Device is Pb–Free, Halogen Free/BFR Free and RoHS
 Compliant

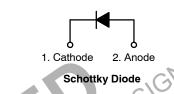
 Applications
 General Purpose
 SMPS, Solar Inverter, UPS
 Power Switching Circuits

 Applications

 ORDFPIN



TO-247-2LD CASE 340CL



MARKING DIAGRAM



- = Assembly Plant Code
- = Date Code (Year & Week)
- = Lot Traceability Code
- = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of

1

Downloaded from Arrow.com.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C unless otherwise noted)

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak Repetitive Reverse Voltage	650	V	
E _{AS}	Single Pulse Avalanche Energy (Note 1)	182	mJ	
lF	Continuous Rectified Forward Current @ T _C <	40	Α	
	Continuous Rectified Forward Current @ T _C <	ontinuous Rectified Forward Current @ T _C < 135°C		
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	1300	Α
		T _C = 150°C, 10 μs	1200	А
I _{F,SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	180	А
I _{F,RM}	Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	85	А
Ptot	Power Dissipation	T _C = 25°C	349	W
		T _C = 150°C	58	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	√ °C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter			Value	Unit
$R_{ hetaJC}$	Thermal Resistance, Junction to Case, Max		50,	0.43	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	$I_F = 40 \text{ A}, T_C = 25^{\circ}\text{C}$	10-11/	1.50	1.75	V
		$I_F = 40 \text{ A}, T_C = 125^{\circ}\text{C}$	0R-11	1.60	2.0	
		$I_F = 40 \text{ A}, T_C = 175^{\circ}\text{C}$	5	1.72	2.4	
I _R	Reverse Current	$V_R = 650 \text{ V}, T_C = 25^{\circ}\text{C}$	ı	-	200	μΑ
	No. Ch.	V _R = 650 V, T _C = 125°C	ı	-	400	
`		V _R = 650 V, T _C = 175°C	-	-	600	
Q_{C}	Total Capacitive Charge	V = 400 V	-	119	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	1989	-	pF
,,,	S OFF.	V _R = 200 V, f = 100 kHz	_	218	_	
	K ,	V _R = 400 V, f = 100 kHz	_	164	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSH4065A	FFSH4065A	TO-247-2LD	30 Units / Tube

^{1.} E_{AS} of 182 mJ is based on starting $T_J = 25^{\circ}C$, L = 0.5 mH, $I_{AS} = 27$ A, V = 50 V.

TYPICAL CHARACTERISTICS

(T_J = 25°C UNLESS OTHERWISE NOTED)

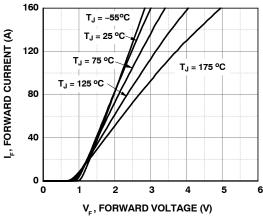


Figure 1. Forward Characteristics

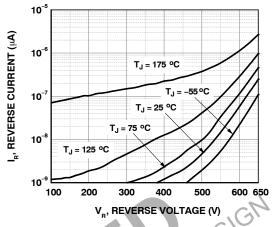


Figure 2. Reverse Characteristics

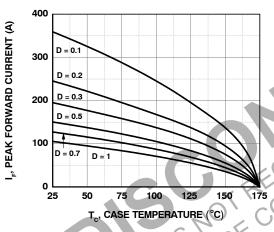


Figure 3. Current Derating

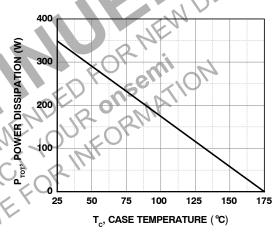


Figure 4. Power Derating

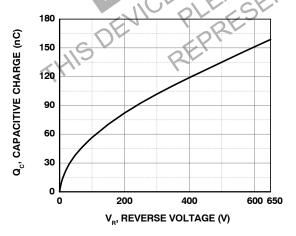


Figure 5. Capacitive Charge vs. Reverse Voltage

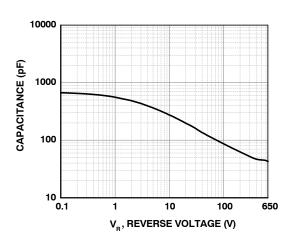


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

(T_J = 25°C UNLESS OTHERWISE NOTED)

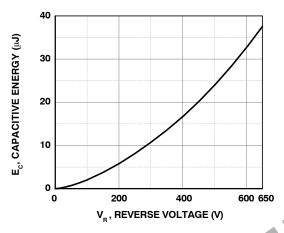
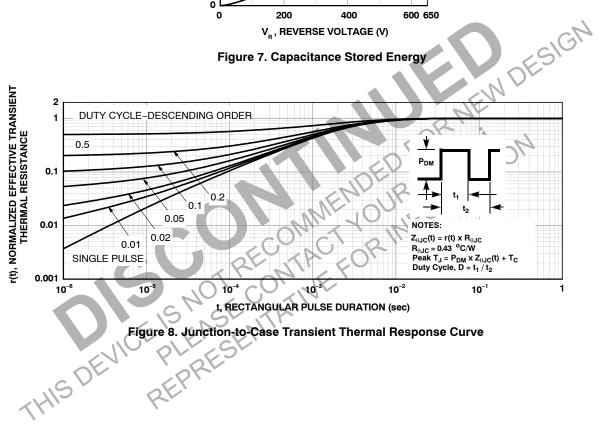
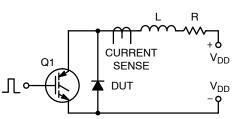


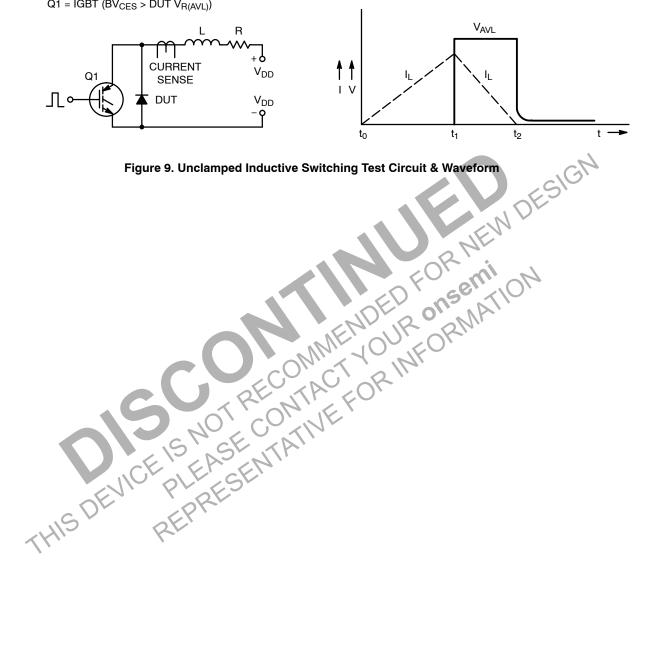
Figure 7. Capacitance Stored Energy



TEST CIRCUIT AND WAVEFORMS

L = 0.5 mH $R < 0.1 \Omega$ $V_{DD} = 50 \text{ V}$ EAVL = 1/2LI2 [V_{R(AVL)} / (V_{R(AVL)} - V_{DD})] Q1 = IGBT (BV_{CES} > DUT V_{R(AVL)})

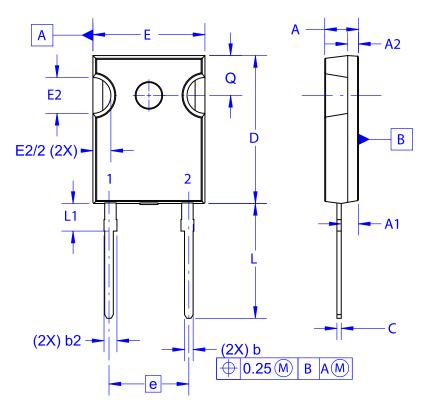




DATE 03 DEC 2019



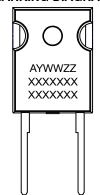






- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

= Assembly Location

= Year

= Work Week WW

= Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

Ø P —		Ø P1 D2
E1 —		D1
		•

DIM	MIL	LIMETER	S
MIN	MIN	NOM	MAX
Α	4.58	4.70	4.82
A1	2.29	2.40	2.66
A2	1.30	1.50	1.70
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
С	0.51	0.61	0.71
D	20.32	20.57	20.82
D1	16.37	16.57	16.77
D2	0.51	0.93	1.35
Е	15.37	15.62	15.87
E1	12.81	~	~
E2	4.96	5.08	5.20
е	~	11.12	~
L	15.75	16.00	16.25
L1	3.69	3.81	3.93
ØΡ	3.51	3.58	3.65
ØP1	6.61	6.73	6.85
Q	5.34	5.46	5.58
S	5.34	5.46	5.58

DOCUMENT NUMBER:	98AON13850G	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	TO-247-2LD		PAGE 1 OF 1		

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems. or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales